

Product Summary

BV _{DSS}	R _{DSON} max	I _D max T _C = +25°C
20V	22mΩ @ V _{GS} = 4.5V	8A
	26mΩ @ V _{GS} = 2.5V	7A

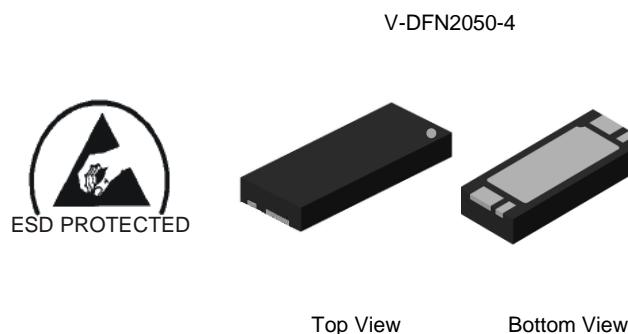
Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative.
<https://www.diodes.com/quality/product-definitions/>

Description and Applications

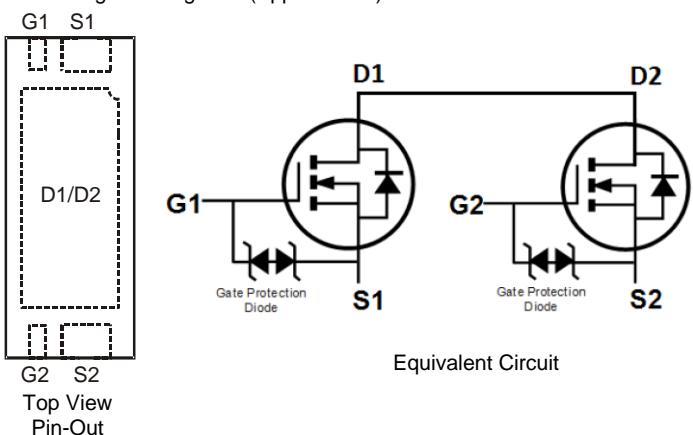
This MOSFET is designed to minimize the on-state resistance (R_{DSON}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- General Purpose Interfacing Switch
- Power Management Functions



Mechanical Data

- Case: V-DFN2050-4
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208^{e4}
- Weight: 0.01 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2024UFX-7	V-DFN2050-4	3,000 / Tape & Reel

Notes:

- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



MEE = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: H = 2020)
 M = Month (ex: 9 = September)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	G	H	I	J	K	L	M	N	O	P	R	S
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V_{GSS}	± 10	V
Continuous Drain Current (Note 6) $V_{GS} = 4.5\text{V}$	Steady State	$T_C = +25^\circ\text{C}$ $T_C = +70^\circ\text{C}$	I_D	8 6	A
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	1.4	A
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)			I_{DM}	40	A
Avalanche Current, $L = 0.1\text{mH}$ (Note 7)			I_{AS}	12	A
Avalanche Energy, $L = 0.1\text{mH}$ (Note 7)			E_{AS}	8	mJ

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Total Power Dissipation (Note 5)	P_D	0.92	W
Thermal Resistance, Junction to Ambient @ $T_A = +25^\circ\text{C}$ (Note 5)	$R_{\theta JA}$	136	$^\circ\text{C}/\text{W}$
Total Power Dissipation (Note 6)	P_D	2.1	W
Thermal Resistance, Junction to Ambient @ $T_A = +25^\circ\text{C}$ (Note 6)	$R_{\theta JA}$	60	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	7.4	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	I_{DSS}	—	—	1	μA	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 8\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(TH)}$	0.5	—	1.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	11 13	22 26	$\text{m}\Omega$	$V_{GS} = 4.5\text{V}, I_D = 4\text{A}$ $V_{GS} = 2.5\text{V}, I_D = 4\text{A}$
Diode Forward Voltage	V_{SD}	—	0.7	1.0	V	$V_{GS} = 0\text{V}, I_S = 5\text{A}$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	—	647	—	pF	$V_{DS} = 10\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	78	—		
Reverse Transfer Capacitance	C_{rss}	—	38	—		
Gate Resistance	R_g	—	400	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ($V_{GS} = 4.5\text{V}$)	Q_g	—	6.5	—	nC	$V_{DS} = 10\text{V}, I_D = 6.5\text{A}$
Total Gate Charge ($V_{GS} = 10\text{V}$)	Q_g	—	14.8	—		
Gate-Source Charge	Q_{gs}	—	1.1	—		
Gate-Drain Charge	Q_{gd}	—	1.7	—		
Turn-On Delay Time	$t_{D(ON)}$	—	98	—	ns	$V_{DS} = 10\text{V}, V_{GS} = 4.5\text{V}, R_G = 6\Omega, R_L = 10\Omega, I_D = 1\text{A}$
Turn-On Rise Time	t_r	—	140	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	1024	—		
Turn-Off Fall Time	t_f	—	434	—		
Body Diode Reverse Recovery Time	t_{RR}	—	245	—	ns	$I_F = 1\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	Q_{RR}	—	149	—	nC	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.

8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.

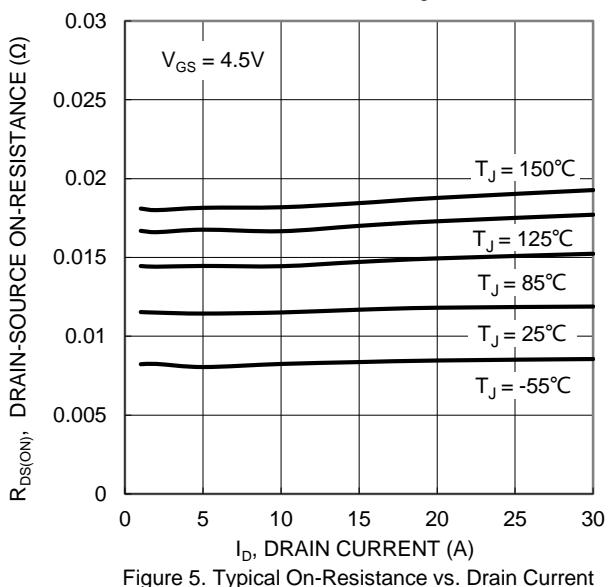
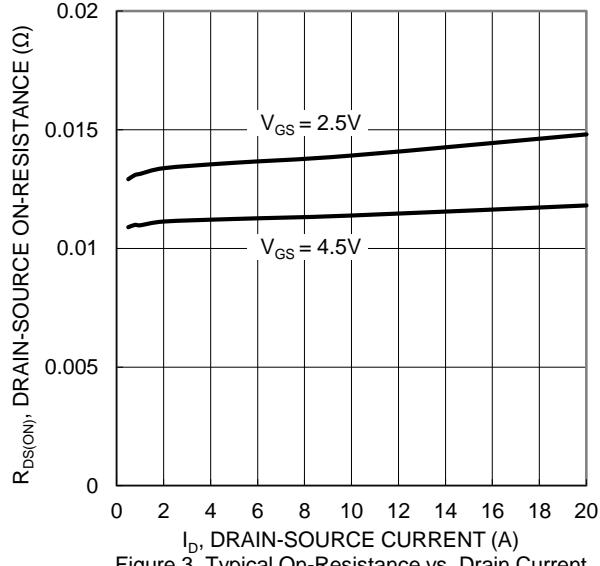
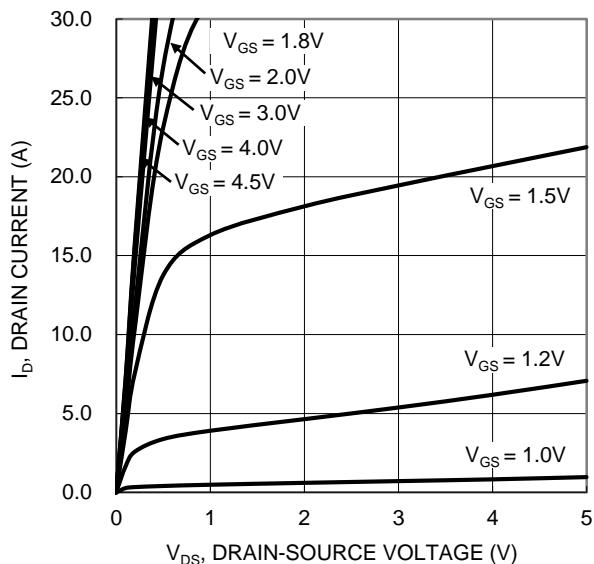
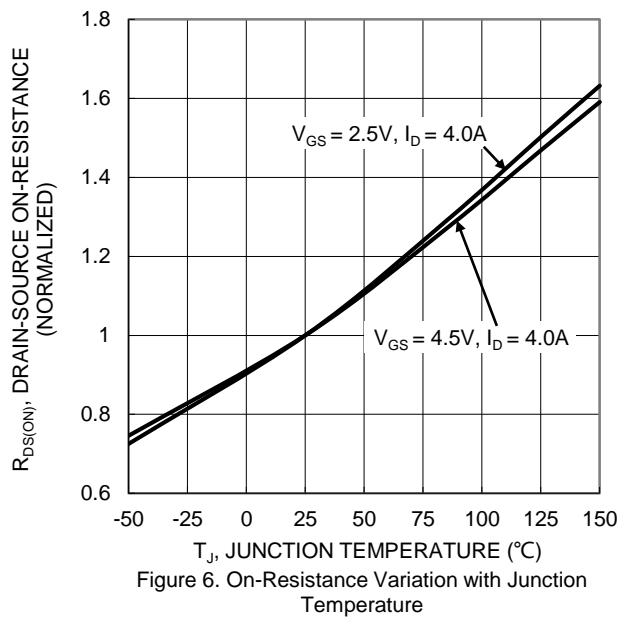
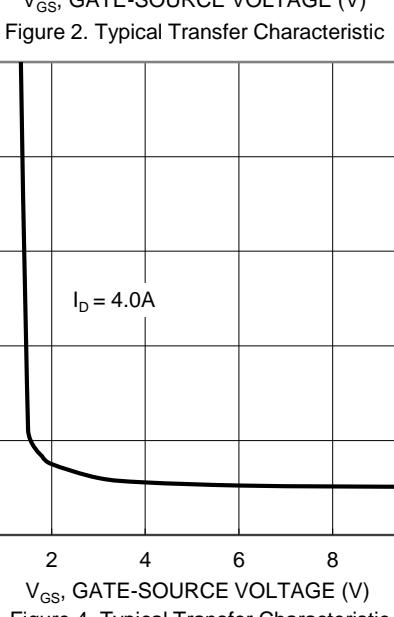
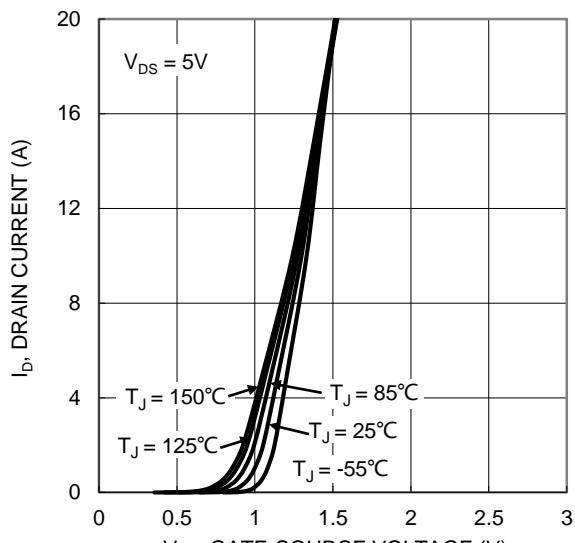


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



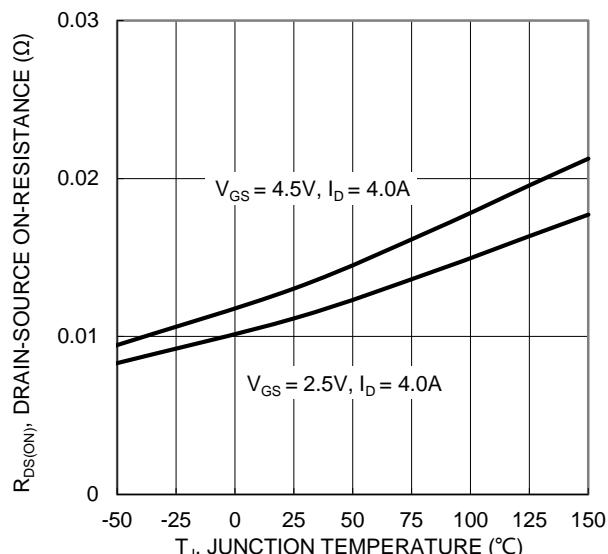


Figure 7. On-Resistance Variation with Junction Temperature

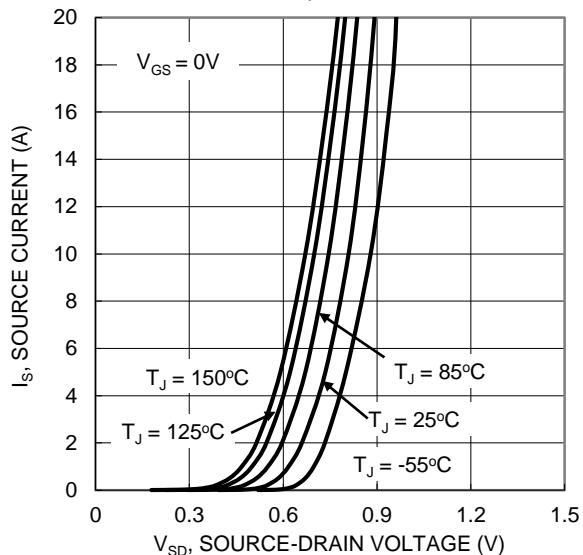


Figure 9. Diode Forward Voltage vs. Current

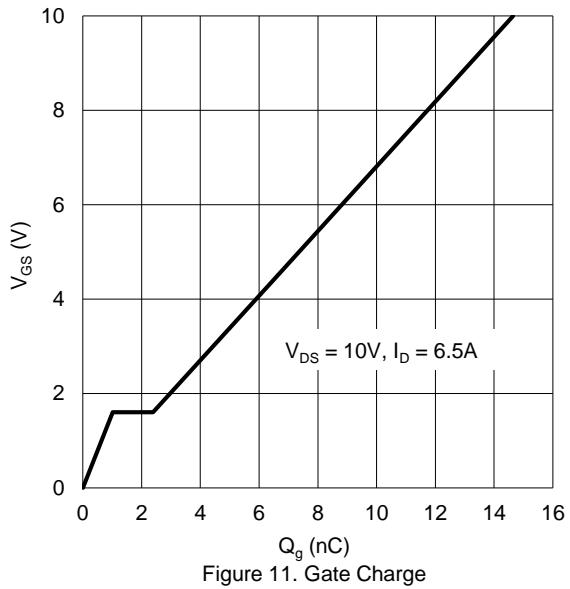


Figure 11. Gate Charge

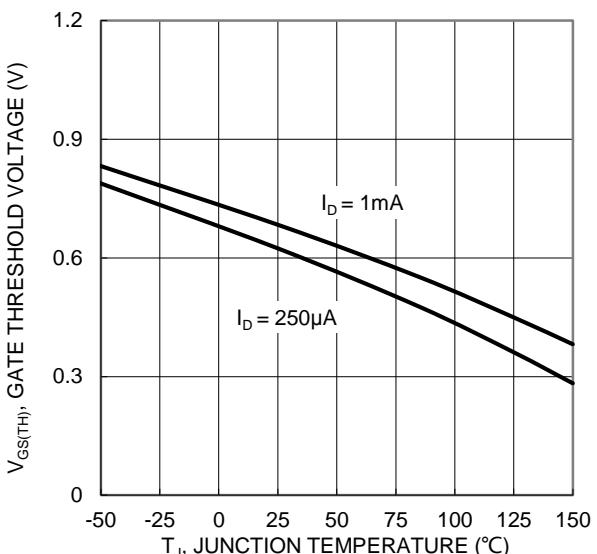


Figure 8. Gate Threshold Variation vs. Junction Temperature

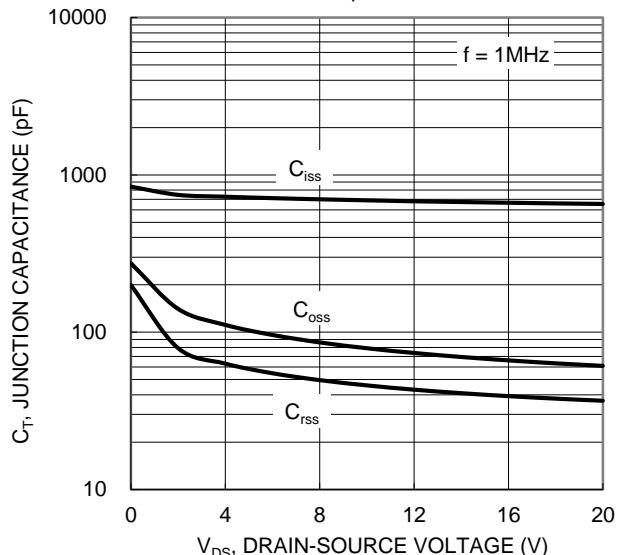


Figure 10. Typical Junction Capacitance

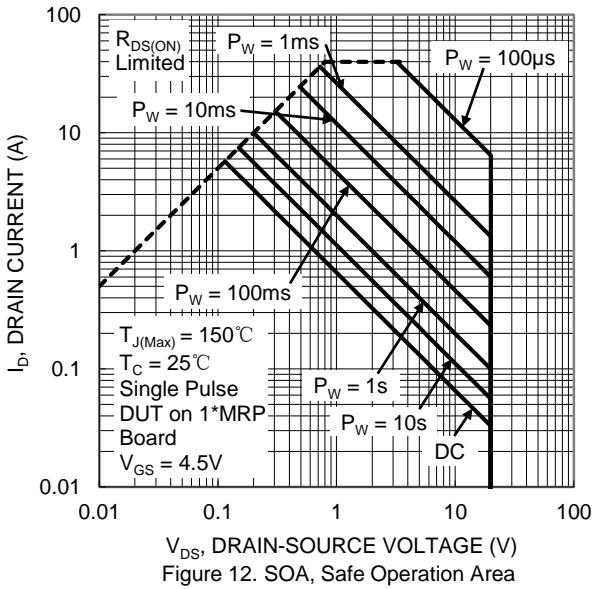


Figure 12. SOA, Safe Operation Area

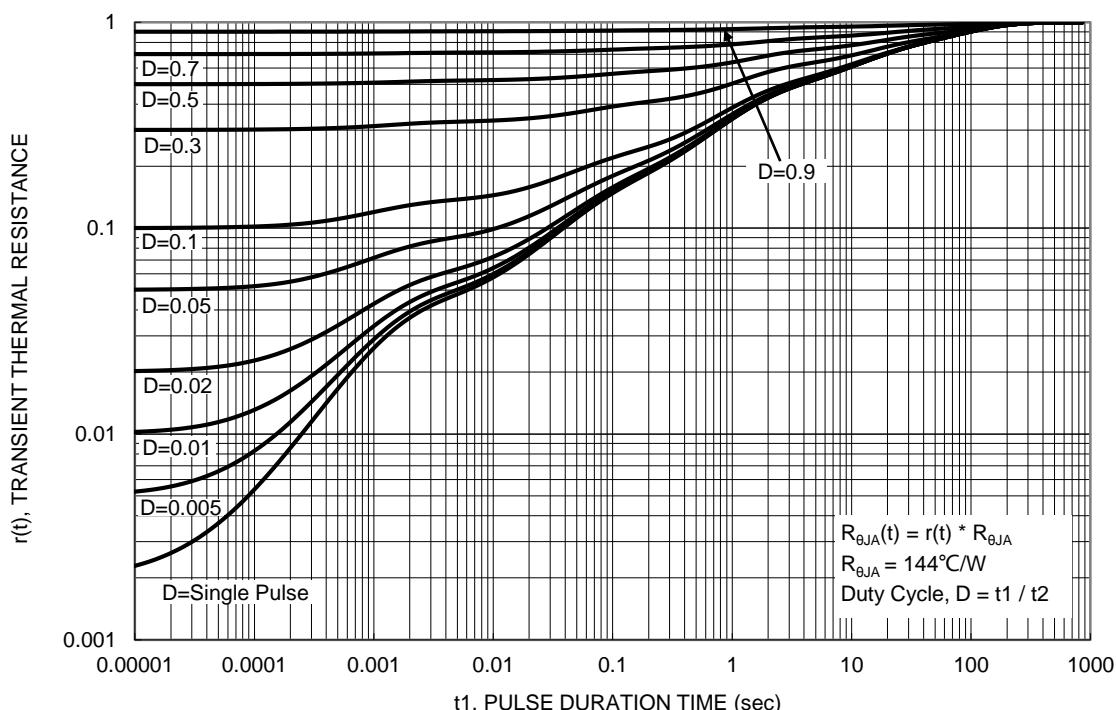
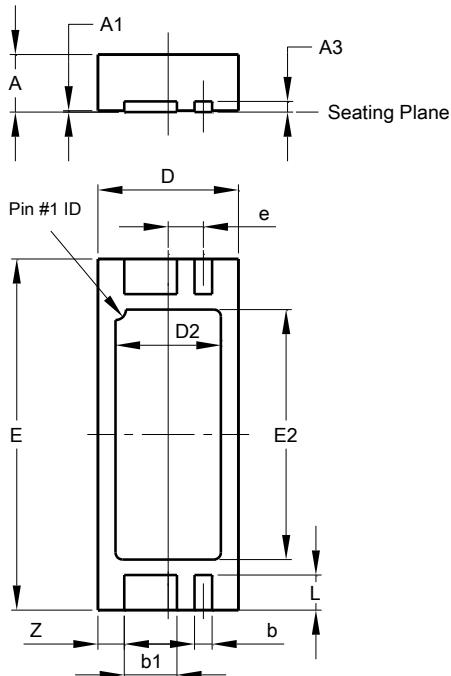


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

V-DFN2050-4



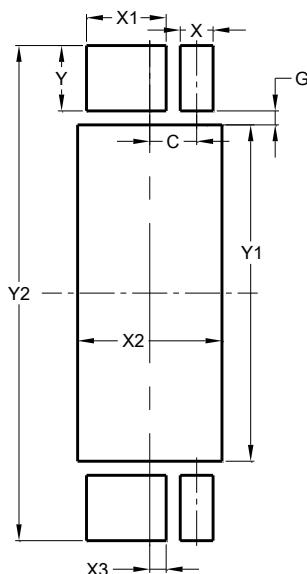
V-DFN2050-4			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0	0.05	0.02
A3	-	-	0.15
b	0.20	0.30	0.25
b1	0.70	0.80	0.75
D	1.90	2.10	2.00
D2	1.40	1.60	1.50
E	4.90	5.10	5.00
E2	3.46	3.66	3.56
e	0.50 BSC		
L	0.35	0.65	0.50
Z	-	-	0.375

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

V-DFN2050-4



Dimensions	Value (in mm)
C	0.500
G	0.150
X	0.350
X1	0.850
X2	1.540
X3	0.175
Y	0.700
Y1	3.600
Y2	5.300

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